

ON Semiconductor		10/15/2019		
Base Part		MC79M	HF	
Orderable Part		MC79M08CTG	Total weight (mg)	1962
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	3.55	Silicon (Si)	7440-21-3	100
Die Attach	82.92	Lead (Pb)	7439-92-1	95
		Tin (Sn)	7440-31-5	5
Lead Frame	1299.13	Iron (Fe)	7439-89-6	0.1
		Copper (Cu)	7440-50-8	99.87
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	543.9	Epoxy resins	n/a	7
		Phenolic Resin	n/a	7
		Silica Amorphous (SiO2)	7631-86-9	15
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	70.5
Plating	31.13	Tin (Sn)	7440-31-5	100
Wire Bond - Cu	1.37	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				